

## Assessment and subject description

<b>Óbuda University</b> Kandó Kálmán Faculty of Electrical Engineering		Institute of Microelectronics and Technology		
Subject name and code: <i>Electronic Technology KMEET11AND</i>				<b>Credits: 3</b>
<b>Full-time, Spring Semester</b>				
Course: Electrical Engineering				
Responsible:	<b>Csikósné Dr Pap Andrea</b>	Teaching staff:	<b>Gröller György</b>	
Prerequisites:	KMEVR12AND			
Contact hours per week:	Lecture: 2	Class discussion: 0	Lab hours: 0	Tutorial: 0
Assessment and evaluation:	exam			
<b>Subject description</b>				
<i>Aims:</i> Review materials and processes used in electronic industry. Constructions of microelectronic parts and devices and their manufacturing methods. Basic technologies of electronic interconnections. Microelectronics is one of the main field of hitech. To understand the advanced products is necessary to know their technological background.				
<i>Topics to be covered:</i>				
<b>Topics</b>			<b>Week</b>	<b>Lessons</b>
<b>Introduction to the technology and electronic industry</b> Discrete parts, substrates, integrated circuits, modules and devices			1	2
<b>Manufacturing of Printed Wiring Boards:</b> patterning; steps of lithography, screen printing, etching, electroless and galvanic plating.			2	2
Single and double side PCB; main steps of production. Multilayer PCB-s, coo-laminated and sequential methods.			3	2
High Density Interconnections (HDI); new requirements, new processes. Control methods. Design for Manufacturing (DfM). <b>Encapsulation;</b> types and footprint of the electronic parts			4	2
<b>Manufacturing of the electronic modules; Surface Mounted Technology (SMT)</b> Soldering basics. Solder paste printing, shooting of devices, reflow soldering.			5	2
SMT II: wave soldering, inspection methods, rework. ESD protection.			6	2
test			7	2
holiday			8	
<b>Hybrid Integrated Circuits (HIC)</b> <i>Thin Film HIC:</i> vacuum deposition methods.			9	2
<i>Thick Film HIC:</i> screen printing methods Thin and thick passive circuits, trimming methods <i>Multichip Modules:</i> types, manufacturing methods			10	2
<b>Introduction to the semiconductor technology:</b> Materials (silicon and compounds semiconductors) Main processes of IC technology: lithography, doping, oxidizing, etching, epitaxy and vacuum deposition methods			10	2
Micro Electro-Mechanical Systems (MEMS)			11	2
holiday			12	2

Printed electronics: materials and technology	13	2
<b>Consultation</b>	14	2
<b>Assessment and evaluation</b>		
<i>Requirements of the signature:</i>	The test result better than 40%	
<i>Type of exam:</i>	Written exam	
<i>Evaluation of the exam:</i>	0 – 49 % 1 50 – 59 % 2 60 – 69 % 3 70 – 84 % 4 85 – 100% 5	
<b>Suggested material</b>		
Gröller György: Electronic technology (presentations and handouts) <a href="http://www.uni-obuda.hu/users/grollerg/Electronic-technology/">http://www.uni-obuda.hu/users/grollerg/Electronic-technology/</a>		
<i>Recommended:</i> Happy Holden: The HDI Handbook <a href="http://www.hdihandbook.com/download.php">http://www.hdihandbook.com/download.php</a>		
Comment:		